

## CLAIMS

1. A thermal printhead comprising:

a plurality of heating resistance sections arranged on  
5 a substrate side by side in a primary scanning direction;

a common wiring portion at least part of which extends  
in the primary scanning direction while being spaced from the  
heating resistance sections in a secondary scanning direction;  
and

10 a plurality of first lead wiring portions and a plurality  
of second lead wiring portions for connecting the heating  
resistance sections to the common wiring portion and to a drive  
IC for controlling energization;

wherein the common wiring portion is segmented into a  
15 plurality of blocks arranged side by side in the primary scanning  
direction, and voltage is applied to opposite ends of each of  
the blocks in the primary scanning direction; and

wherein the plurality of heating resistance sections are  
segmented into a plurality of other blocks corresponding to  
20 the blocks of the common wiring portion, and, in each of said  
other blocks, resistance of the heating resistance sections  
reduces as proceeding from opposite ends toward center of the  
block in the primary scanning direction.

25 2. The thermal printhead according to claim 1, wherein the  
plurality of first lead wiring portions are generally equal  
to each other in resistance, and the plurality of second lead

wiring portions are generally equal to each other in resistance.

3. The thermal printhead according to claim 2, wherein the first lead wiring portions are unequal in length, and the second lead  
5 wiring portions are unequal in length, wherein a longer one of the lead wiring portions has a larger width at least partially.
4. The thermal printhead according to claim 1, wherein a plurality of drive ICs are provided, and each of the drive ICs corresponds  
10 to a respective one of said other blocks of the heating resistance sections.
5. The thermal printhead according to claim 1, further comprising a plurality of third lead wiring portions each connecting  
15 adjacent pair of the heating resistance sections, arranged in the primary scanning direction;  
wherein the drive IC is arranged closer to the common wiring portion than to the heating resistance sections in the secondary scanning direction; and  
20 wherein the first lead wiring portions and the second lead wiring portions are alternately arranged in the primary scanning direction to be connected to respective pairs of the heating resistance sections and extend from the heating resistance sections toward the common wiring portion.